506595106 04/06/2021

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT6641910

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
MATTHEW J. KING	08/28/2020
DAVID A. DAYCOCK	08/20/2020
YOSHIAKI FUKUZUMI	08/28/2020
ALBERT FAYRUSHIN	08/20/2020
RICHARD J. HILL	08/25/2020
CHANDRA S. TIWARI	08/20/2020
JUN FUJIKI	08/26/2020

RECEIVING PARTY DATA

Name:	MICRON TECHNOLOGY, INC.
Street Address:	8000 SOUTH FEDERAL WAY, MAILSTOP 1-507
City:	BOISE
State/Country:	IDAHO
Postal Code:	83707-0006

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17007951

CORRESPONDENCE DATA

Fax Number: (801)531-9168

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 8015321922

Email: mebriggs@traskbritt.com

Correspondent Name: TRASKBRITT

Address Line 1: 230 SOUTH 500 EAST, SUITE 300
Address Line 4: SALT LAKE CITY, UTAH 84102

ATTORNEY DOCKET NUMBER:	2269-15604(2019-2529.00
NAME OF SUBMITTER:	ELIZABETH HERBST SCHIERMAN
SIGNATURE:	/Elizabeth Herbst Schierman/
DATE SIGNED:	04/06/2021

PATENT 506595106 REEL: 055844 FRAME: 0878

Total Attachments: 21 source=2021-04-06-Assignments-2020-15604US#page1.tif source=2021-04-06-Assignments-2020-15604US#page2.tif source=2021-04-06-Assignments-2020-15604US#page3.tif source=2021-04-06-Assignments-2020-15604US#page4.tif source=2021-04-06-Assignments-2020-15604US#page5.tif source=2021-04-06-Assignments-2020-15604US#page6.tif source=2021-04-06-Assignments-2020-15604US#page7.tif source=2021-04-06-Assignments-2020-15604US#page8.tif source=2021-04-06-Assignments-2020-15604US#page9.tif source=2021-04-06-Assignments-2020-15604US#page10.tif source=2021-04-06-Assignments-2020-15604US#page11.tif source=2021-04-06-Assignments-2020-15604US#page12.tif source=2021-04-06-Assignments-2020-15604US#page13.tif source=2021-04-06-Assignments-2020-15604US#page14.tif source=2021-04-06-Assignments-2020-15604US#page15.tif source=2021-04-06-Assignments-2020-15604US#page16.tif source=2021-04-06-Assignments-2020-15604US#page17.tif source=2021-04-06-Assignments-2020-15604US#page18.tif source=2021-04-06-Assignments-2020-15604US#page19.tif source=2021-04-06-Assignments-2020-15604US#page20.tif source=2021-04-06-Assignments-2020-15604US#page21.tif

Attorney Docket No. 2269-P15604US (2019-2529.00/US)

ASSIGNMENT

FOR GOOD AND VALUABLE CONSIDERATION, the receipt, sufficiency and adequacy of which are hereby acknowledged, each undersigned ASSIGNOR does hereby:

SELL, ASSIGN AND TRANSFER to MICRON TECHNOLOGY, INC. ("ASSIGNEE"), a corporation of the State of Delaware, having a place of business at 8000 South Federal Way, Mailstop 1-507, Boise, ID 83707-0006, the entire right, title and interest for the United States and all foreign countries in and to any and all improvements that are disclosed in the Application for United States Letters Patent that has been executed by each undersigned ASSIGNOR concurrently herewith, and titled MICROELECTRONIC DEVICES INCLUDING ISOLATION STRUCTURES PROTRUDING INTO UPPER PILLAR PORTIONS, AND RELATED METHODS AND SYSTEMS, such application and all divisional, continuing, substitute, renewal, reissue and all other applications for patent or the legal equivalent thereof that have been or may be filed in the United States and all foreign countries relating to any of such improvements; all original, reexamined and reissued patents that have been or shall be issued in the United States and all foreign countries on such improvements; and specifically including the right to file foreign applications under the provisions of any convention or treaty and claim priority based on such application made in the United States;

AUTHORIZE the ASSIGNEE to apply for and receive any and all United States and foreign patents relating to such improvements in its own name;

AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign patents granted on such improvements to and in the name of the ASSIGNEE;

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COVENANT, when requested and at the expense of the ASSIGNEE, to carry out in good faith the intent and purpose of this Assignment, to execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications relating to any and all such improvements; to execute all rightful oaths, declarations, assignments, powers of attorney and other papers; to communicate to the ASSIGNEE all facts and provide to the ASSIGNEE all documents and things known and accessible to the undersigned relating to such improvements and the history thereof, and testify as to the same in any interference, litigation or other proceeding relating thereto; and generally to do everything possible that the ASSIGNEE shall consider desirable for vesting title to such improvements in the ASSIGNEE, and to secure, maintain, defend and enforce valid and enforceable patent protection for such improvements;

ASSIGNOR(S):	
/Matthew J. King/ Matthew J. King Residing at: 6272 North Stafford Place, Boise, ID 83713	Date: 8/28/2020
David A. Daycock Residing at: 153 Woodgrove Ave., Woodhaven, Singapo	Date:
Yoshiaki Fukuzumi Mailing address: c/o Micron Memory Japan, G.K., 8th Konan, Minato-ku, Tokyo 108-0075 Japan	Date:
Albert Fayrushin Residing at: 3660 E Warm Springs Avenue, Boise, ID 83	Date:
Richard J. Hill Residing at: 636 N Morningside Way, Boise, ID 83712	Date:

2

Chandra S. Tiwari Residing at: 4633 East Flores Court, Boise, ID 83716	Date:
T. T. ''.	Date:
Jun Fujiki	
Mailing address: c/o Micron Memory Japan, G.K., 8th flo Konan, Minato-ku, Tokyo 108-0075 Japan	or, Shinagawa Season Terrace, 1-2-70,

3

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ASSIGNOR(S):		
	Date:	
Matthew J. King Residing at: 6272 North Stafford Place, Boise, ID 8371		
	Date: 20 August 2020	
Residing at: 153 Woodgrove Ave., Woodhaven, Singa	apore 737849, Singapore	
	Date:	
Yoshiaki Fukuzumi Mailing address: c/o Micron Memory Japan, G.K., 8 Konan, Minato-ku, Tokyo 108-0075 Japan	8th floor, Shinagawa Season Terrace, 1-2-	70,
Albert Fayrushin	Date:	
Residing at: 3660 E Warm Springs Avenue, Boise, ID	9 83716	
Richard J. Hill Residing at: 636 N Morningside Way, Boise, ID 83712	Date:	
	Date:	
Chandra S. Tiwari Residing at: 4633 East Flores Court, Boise, ID 83716		

Date:
Jun Fujiki
Mailing address: c/o Micron Memory Japan, G.K., 8th floor, Shinagawa Season Terrace, 1-2-70,
Konan, Minato-ku, Tokyo 108-0075 Japan

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David A. Daycock Residing at: 153 Woodgrove Ave., Woodhaven, Singapa	Date: ore 737849, Singapore	
Yogh ia le Fiskery. Yoghaki Fukuzumi Mailing address: c/o Micron Memory Japan, G.K., 8th Konan, Minato-ku, Tokyo 108-0075 Japan		
Albert Fayrushin Residing at: 3660 E Warm Springs Avenue, Boise, ID 8	Date:	
Richard J. Hill Residing at: 636 N Morningside Way, Boise, ID 83712	Date:	
Chandra S. Tiwari	Date:	

Residing at: 4633 East Flores Court, Boise, ID 83716

	Date:
Jun Fujiki	
Mailing address: c/o Micron Memory Japan, G.K., 8th floor	r, Shinagawa Season Terrace, 1-2-70,
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Albert Fayruskin Residing at: 3660 E Warm Springs Avenue, Boise, ID 83	Date: <u>8-20 - ?</u> 716	<u>,020</u>
Richard J. Hill Residing at: 636 N Morningside Way, Boise, ID 83712	Date:	
Chandra S. Tiwari	Date:	

Residing at: 4633 East Flores Court, Boise, 1D 83716

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	Date: _	
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Albert Fayrushin Residing at: 3660 E Warm Springs Avenue, Boise, ID 8	Date: _	
Residing at. 3000 E warm springs Avenue, Boise, ID o	53 / 10	
/Richard Hill/ Richard J. Hill Residing at: 636 N Morningside Way, Boise, ID 83712	Date: _	8/25/20
Chandra S. Tiwari Residing at: 4633 East Flores Court, Boise, ID 83716	Date: _	

Date:
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Yoshiaki Fukuzumi Mailing address: c/o Micron Memory Japan, G.K., 8t Konan, Minato-ku, Tokyo 108-0075 Japan	Date: h floor, Shin	agawa Season Terrace, 1-2-70,
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Richard J. Hill Residing at: 636 N Morningside Way, Boise, ID 83712	Date:	
/Chandra Tiwari/ Chandra S. Tiwari Residing at: 4633 East Flores Court, Boise, ID 83716	Date:	8/20/2020

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	Date:	
Matthew J. King Residing at: 6272 North Stafford Place, Boise, ID 837	713	
David A. Davagala	Date:	
David A. Daycock Residing at: 153 Woodgrove Ave., Woodhaven, Singa	gapore 737849, Singapore	
V 1: 1: E 1	Date:	
Yoshiaki Fukuzumi Mailing address: c/o Micron Memory Japan, G.K., 8 Konan, Minato-ku, Tokyo 108-0075 Japan	8th floor, Shinagawa Season Terrace, 1-2-	-70,
Albert Fayrushin	Date:	
Residing at: 3660 E Warm Springs Avenue, Boise, ID	7 83 / 10	
Richard J. Hill Residing at: 636 N Morningside Way, Boise, ID 8371	Date:	
Chandra S. Tiwari	Date:	
Residing at: 4633 East Flores Court, Boise, ID 83716	ı	

/Jun Fujiki/	Date:	26 August 2020
Jun Fujiki		

Mailing address: c/o Micron Memory Japan, G.K., 8th floor, Shinagawa Season Terrace, 1-2-70, Konan, Minato-ku, Tokyo 108-0075 Japan

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RECORDED: 04/06/2021